

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 2002-043497

(43)Date of publication of application : 08.02.2002

51)Int.CI. H01L 23/50

21)Application number : 2000-227077 (71)Applicant : MITSUBISHI ELECTRIC CORP

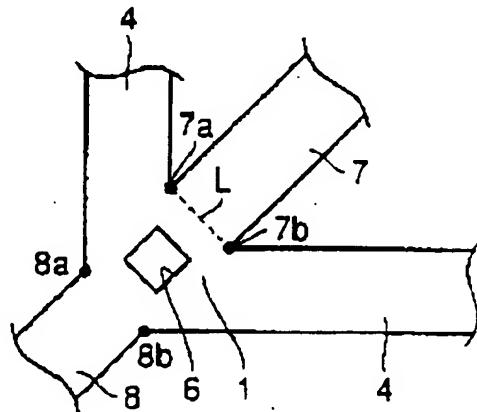
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54) SEMICONDUCTOR DEVICE

57)Abstract:

PROBLEM TO BE SOLVED: To provide a semiconductor device having a resin peeling prevention hole and provided with a lead frame difficult to concentrate deformation in the neighborhood thereof.

SOLUTION: The resin peeling prevention hole 5 is provided on the intersection part 1 of a reinforcing frame 4 and an inside hanging lead in the lead frame, and positioned on the intersection part of the area of the contrary side of a die pad rather than a line L connecting first and second inside hanging lead root boundary points 7a, 7b being a point in which the reinforcing frame continues to both the side parts of an inside hanging lead extending from the intersection part.



LEGAL STATUS

Date of request for examination]

Date of sending the examiner's decision of rejection]

Kind of final disposal of application other than the
examiner's decision of rejection or application
converted registration]

Date of final disposal for application]

Patent number]

Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

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